The Mid-Hudson Valley EPS Chapter hosted and organized a Mini Colloquium on Advanced Technology for Inter-Chiplet Connectivity in August 2022. It was open to all students and professionals, regardless of IEEE or EPS membership status. We invited subject matter experts and technology leaders in the various areas of electronic packaging to educate and inform our audience. A total of 112 individuals registered for this on site in person event at the SUNY CNSE / IBM Research Campus in Albany, New York.

The event was posted on Vtools, and publicized through various channels, including EPS, IEEE Region 1 announcements, and internally in various organizations and academic institutions, through email. Registration was free to all. The EPS MHV Chapter provided a mid-morning break with coffee, juice, and light refreshments. The attendees gave the chapter accolades in person because of the timely subject matter and the expertise of the speakers.

The list of volunteer organizers of the EPS MHV is as follows:

Mukta Farooq - Chair; Katsuyuki Sakuma - Vice Chair; Aakrati Jain – Chapter Secretary, Sathya Raghavan – Treasurer, James Kelly – Program Chair, Eric Perfecto – Membership Chair.

On behalf of all the organizers, I would like to express our gratitude to K. Pearsall and EPS for the funding, to the instructors for the great lectures, and to the attendees for making this a fruitful venture. We hope to continue this effort in the future.

- *Mukta Farooq, IEEE Fellow, Sept 29, 2022*

The Speakers and the Organizing Committee for 2022 IEEE EPS Mid-Hudson Valley Chapter Mini-Colloquium. (*From left to right)* Jim Kelly, Katsuyuki Sakuma, Aakrati Jain, Mukta Ghate Farooq, Vineet Pancholi, Junghyun Cho, Ning-Cheng Lee, Tanja Braun, Sathya Raghavan, and Eric Perfecto.

Mini Colloquium on Advanced Technology for Inter-Chiplet Connectivity

Presented by

2022 IEEE Electronics Packaging Society Mid-Hudson Valley Chapter

Date: 11 August 2022
Time: 8:30 am to 12:30 pm
Location: CNSE Auditorium NFS103, Albany NanoTech Complex

Free Registration for ALL!

Mid-session coffee and snacks included!

To reserve your spot, please REGISTER at:
https://events.vtools.ieee.org/m/320609

Register using QR code:

Topics and Speakers

Test Impacts of Multi-Die Packages
Vineet Pancholi
Senior Director, Amkor Technologies Inc.

Material Considerations for High Reliability Pb-Free Solder Joints
Dr. Ning-Cheng Lee
Founder, ShinePure Hi-Tech
Ex-Vice-President, Indium Corporation

Advanced Packaging – Key for Heterogeneous Integration
Dr. Tanja Braun
Lead Engineer, Fan-out Panel Level Packaging Consortium, Fraunhofer IZM

Bonding Technologies toward Ultra-fine Pitch 3D Interconnection
Dr. Junghyun Cho
Professor, Dept. of Mechanical Engineering
Binghamton University

Sponsored by: